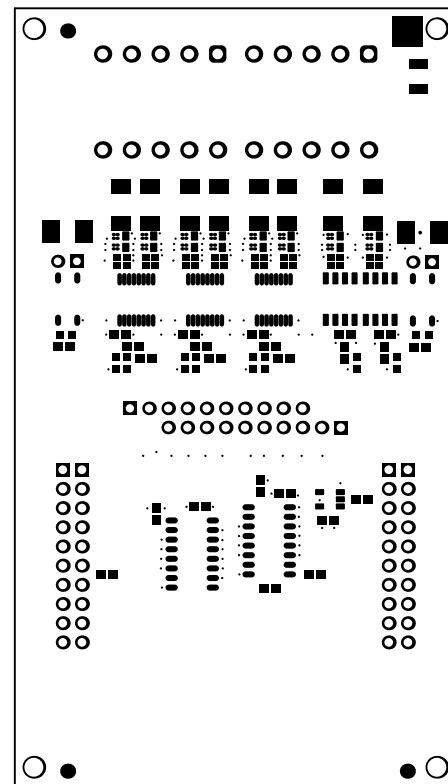
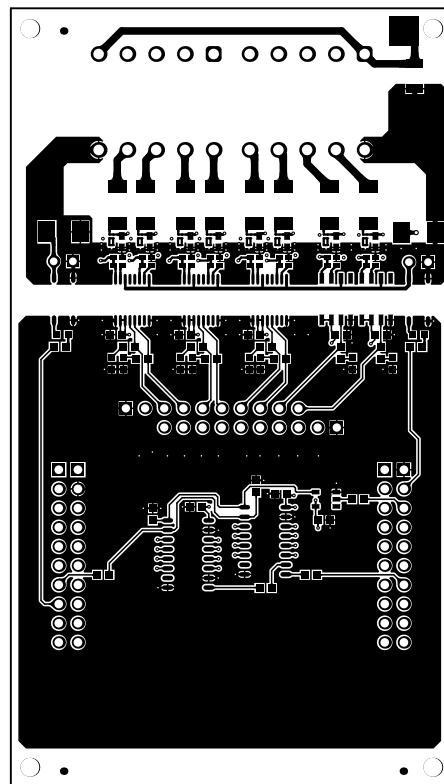


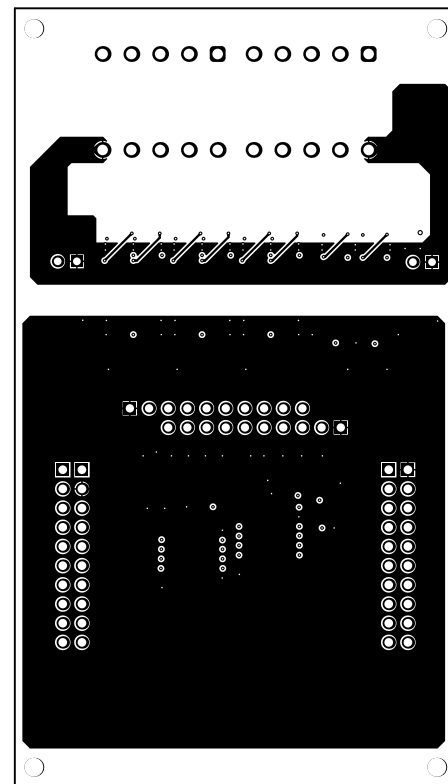
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01508	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01508		
PLOT NAME = Top Overlay	GENERATED : 20.11.2017 13:30:09	TEXAS INSTRUMENTS	



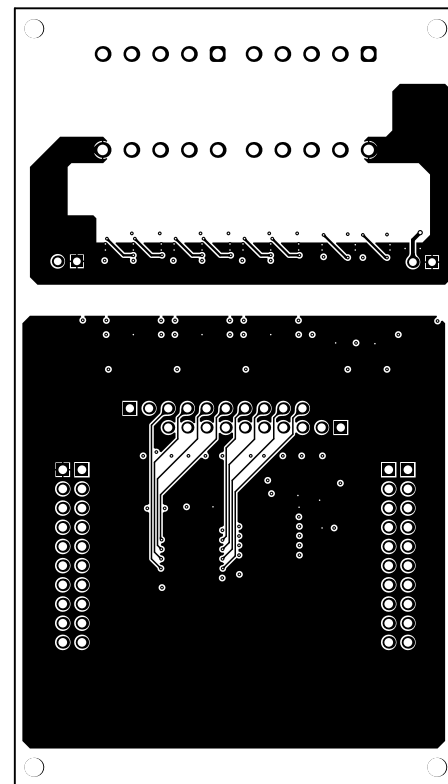
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01508	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01508		
PLOT NAME = Top Solder Mask	GENERATED : 20.11.2017 13:30:10	TEXAS INSTRUMENTS	



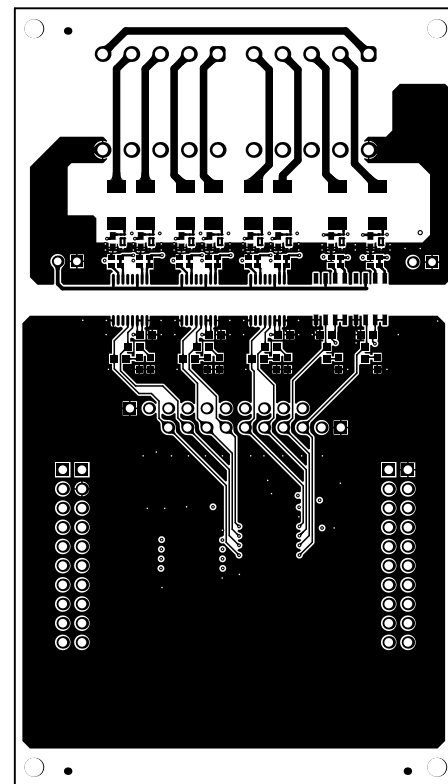
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01508	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01508		
PLOT NAME = Top Layer	GENERATED : 20.11.2017 13:30:11	TEXAS INSTRUMENTS	



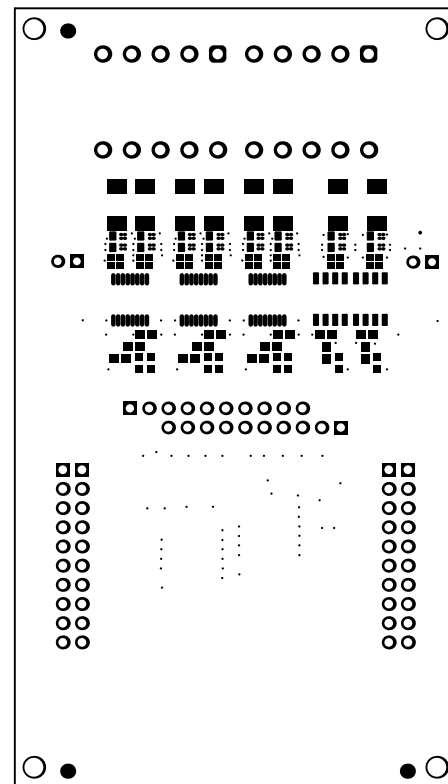
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01508	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = GND	TID #: TIDA-01508		
PLOT NAME = Signal Layer 1	GENERATED : 20.11.2017 13:30:12	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01508	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = UCC	TID #: TIDA-01508		
PLOT NAME = Signal Layer 2	GENERATED : 20.11.2017 13:30:13	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01508	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01508		
PLOT NAME = Bottom Layer	GENERATED : 20.11.2017 13:30:14	TEXAS INSTRUMENTS	

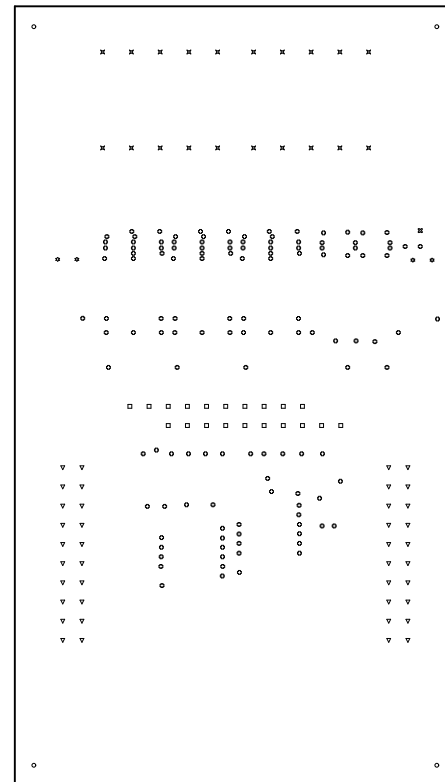


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01508	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01508		
PLOT NAME = Bottom Solder Mask	GENERATED : 20.11.2017 13:30:15	TEXAS INSTRUMENTS	

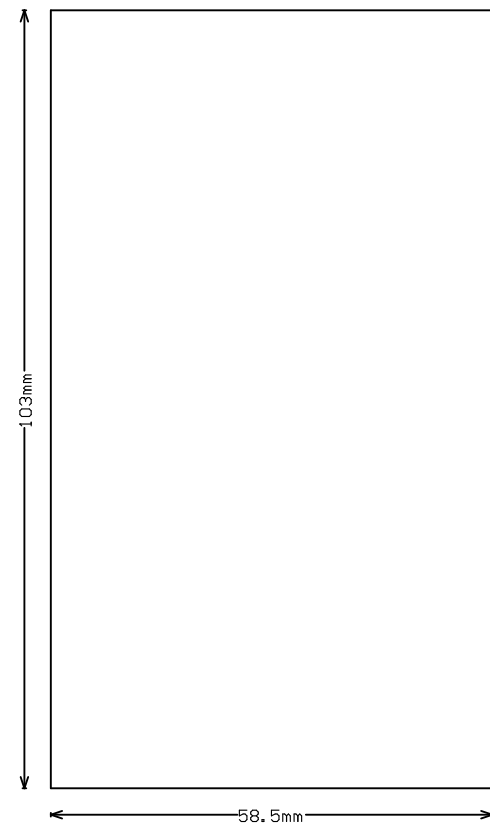


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01508	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01508		
PLOT NAME = Bottom Overlay	GENERATED : 20.11.2017 13:30:16	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	4	2,500mm (98,43mil)	NPTH	Round	Top Layer - Bottom Layer	
⊗	129	0,200mm (7,87mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	1	0,400mm (15,75mil)	PTH	Round	Top Layer - Bottom Layer	
☆	4	1,020mm (40,16mil)	PTH	Round	Top Layer - Bottom Layer	
□	20	1,100mm (43,31mil)	PTH	Round	Top Layer - Bottom Layer	
▽	40	1,150mm (45,28mil)	PTH	Round	Top Layer - Bottom Layer	
⊗	20	1,400mm (55,12mil)	PTH	Round	Top Layer - Bottom Layer	+/-0,200mm
	218 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01508	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01508		
PLOT NAME = Drill Drawing	GENERATED : 20.11.2017 13:30:17	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01508	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01508		
PLOT NAME = Board Dimensions	GENERATED : 20.11.2017 13:30:19		TEXAS INSTRUMENTS

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